

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	70344	solid near10 resin	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 12:07
L2	23277	1 and mold\$3	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 12:07
L3	12686	2 and (cavity open\$3 recess)	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 12:07
L4	1288	3 and ((top upper) near5 mold)	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 11:38
L6	1323	3 and ((bottom lower) near5 mold)	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 11:38
L7	912	4 and 6	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 11:39
L8	209	7 and (electronic semiconductor)	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/26 11:39
L9	29729	solid near10 resin	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/26 12:07
L10	2341	9 and mold\$3	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/26 12:07
L11	246	10 and (cavity open\$3 recess)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/26 12:07